



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31C680KGFNNNF

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 68pF, 500V, ±10%, C0G, 1206

## A. Samsung Part Number

<u>CL</u> <u>31</u> <u>C</u> <u>680</u> <u>K</u> <u>G</u> <u>F</u> <u>N</u> <u>N</u> <u>N</u> <u>F</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor		
2	Size	1206 (inch code)	L: 3.2 ± 0.15 mm W: 1.6 ±	0.15 mm
3	Dielectric	C0G	8 Inner electrode Ni	
4	Capacitance	<b>68</b> pF	<b>Termination</b> Cu	
⑤	Capacitance	±10 %	Plating Sn 1009	% (Pb Free)
	tolerance		Product Normal	
6	Rated Voltage	500 V	<b>10 Special</b> Reserve	ed for future use
7	Thickness	1.25 ± 0.15 mm	Packaging Emboss	sed Type, 13" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms		
Q	1000 min			
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.		
Resistance	Whichever is Smaller			
Appearance	No abnormal exterior appearance	Microscope (×10)		
Withstanding	No dielectric breakdown or	150% of the rated voltage		
Voltage	mechanical breakdown			
Temperature	COG			
Characterisitcs	(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change shoud be within ±30PPM/ $^{\circ}$ C)			
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change :	Bending to the limit (1mm)		
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5℃, 3±0.3sec.		
		(preheating : 80~120°C for 10~30sec.)		
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	within ±2.5% or ±0.25pF whichever is larger	r is larger		
	Tan δ, IR : initial spec.			

	Performance	Test condition	
Vibration Test	Capacitance change :	Amplitude : 1.5mm	
within ±2.5% or ±0.25pF whichever is la		From 10Hz to 55Hz (return : 1min.)	
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)	
Moisture	Capacitance change :	With rated voltage	
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs	
	Q: 200 min		
	IR : 500Mohm or 25Mohm $\cdot \mu$ F		
	Whichever is Smaller		
High Temperature	Capacitance change :	With 150% of the rated voltage	
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature	
	Q: 350 min	1000+48/-0hrs	
	IR : 1000Mohm or 50Mohm · μF		
	Whichever is Smaller		
Temperature	Capacitance change :	1 cycle condition	
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25°C	
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C	
		5 cycle test	

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.